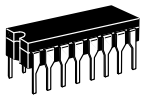
Dual 4-Input OR/NOR Gate

MC1660

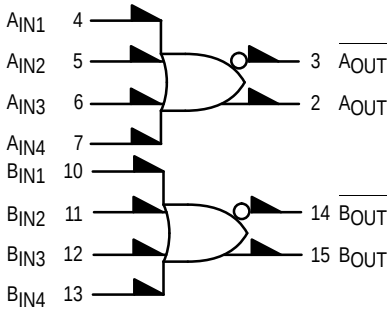
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	–30°C		+25°C		+85°C		Unit
		Min	Max	Min	Max	Min	Max	
Power Supply Drain Current	I_E	—	—	—	28	—	—	mAdc
Input Current	I_{inH}	—	—	—	350	—	—	μAdc
Switching Times Propagation Delay	t^{+-} t^{-+}	0.6 0.6	1.8 1.6	0.6 0.6	1.7 1.5	0.6 0.6	1.9 1.7	ns
Rise Time, Fall Time (10% to 90%)	t^+, t^-	0.6	2.2	0.6	2.1	0.6	2.3	ns



L SUFFIX
CERAMIC PACKAGE
CASE 620–10

LOGIC DIAGRAM



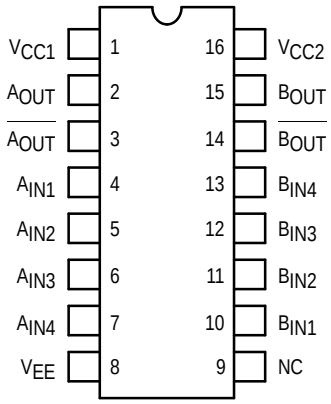
$$\overline{OUT} = IN1 + IN2 + IN3 + IN4$$
$$OUT = \overline{IN1 + IN2 + IN3 + IN4}$$

V_{CC1} = PIN 1
V_{CC2} = PIN 16
V_{EE} = PIN 8

t_{pd} = 0.9 ns typ (510 ohm load)
= 1.1 ns typ (50 ohm load)

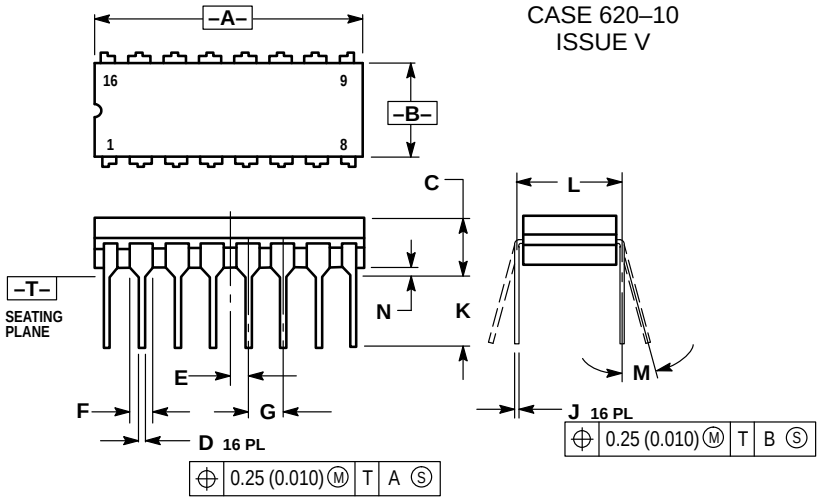
P_D = 120 mW typ/pkg (No load)
Full Load Current, I_L = –25 mAdc max

PIN ASSIGNMENT



OUTLINE DIMENSIONS

L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE V



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

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